

## 1. 2020 년 교육 계획

분기	차수	일시	내용	정원
1/4	55 차	2020.01.16	<u>Basic Course:</u> Microstructures Sample preparation for Metallurgy	10 명
	56 차	2020.02.13	<u>Basic Course:</u> Microstructures Sample preparation for Electronic Materials	10 명
	82 차	2020.03.12	<u>MultiPrep System Users Meeting:</u> Cross-Section/ TEM Wedge Sample Preparation	6 명
2/4	57 차	2020.04.09	<u>Basic Course:</u> Microstructures Sample preparation for Metallurgy	10 명
	58 차	2020.05.14	<u>Basic Course:</u> Microstructures Sample preparation for Electronic Materials	10 명
	83 차	2020.06.11	<u>MultiPrep System Users Meeting:</u> Parallel Thinning for Die & Package Analysis	6 명
3/4	59 차	2020.07.09	<u>Basic Course:</u> Microstructures Sample preparation for Metallurgy	10 명
	60 차	2020.08.20	<u>Basic Course:</u> Microstructures Sample preparation for Electronic Materials	10 명
	84 차	2020.09.17	<u>MultiPrep System Users Meeting:</u> Cross-Section/ TEM Wedge Sample Preparation	6 명
4/4	61 차	2020.10.15	<u>Basic Course:</u> Microstructures Sample preparation for Metallurgy	10 명
	62 차	2020.11.12	<u>Basic Course:</u> Microstructures Sample preparation for Electronic Materials	10 명
	85 차	2020.12.10	<u>MultiPrep System Users Meeting:</u> Parallel Thinning for Die & Package Analysis	6 명